

ISTFA 2026 schedule

Visit us at booth #501

Technical program

Tuesday, October 6		
Integrated PFIB Delayering and In-Situ AFM-Based Electrical Characterization for Rapid, Site-Specific 3D Failure Analysis of Advanced-Node Devices	Jamie Gravell	10:10 a.m. (Room 205)
Deep Learning-Based 2D ROI Alignment for Automated Semiconductor SEM Imaging	Youngchan Choi	12:50 p.m. (Room 206 A-B)
Wednesday, October 7		
Electron Beam Probing for Advanced Nodes Using Video-rate Waveform Acquisitions	Neel Leslie	04:20 p.m. (Bridge Hall)
Thursday, October 8		
A Novel Accurate Thickness Measurement Method Using Specific Structure within a DRAM Sample and Tilt Adjustment	Hyoung-sic Cho	09:00 a.m. (Room 206 A-B)
Enhancing Cross-Sectional Milling Performance in Plasma Focused Ion Beam Using Shadow Masking	Jesun Baek	10:20 a.m. (Bridge Hall)
Ultra-Thin, Structure-Targeted TEM Lamella Preparation Using Multi-Ion PFIB Systems	Hunter Good	11:00 a.m. (Bridge Hall)
Automated Navigation Framework for High-Density 3D VNAND using Structural Periodicity-Based Address Mapping and Computer Vision	Minji Seo, Samsung Electronics, with Thermo Fisher Scientific	11:20 a.m. (Room 205)

Chaired sessions

Sunday, October 4		
Package Analysis	Session co-chair: Melissa Sundar	04:20 p.m. (Bridge Hall)
Tuesday, October 6		
Nanoprobng & Electrical Characterization	Session co-chair: John Sanders	10:10 a.m. (Room 205)
Wednesday, October 7		
Power Devices (Si, SiC, GaN)	Session co-chair: Christopher Kang	04:20 p.m. (Room 206 A-B)
Thursday, October 8		
System in Package and 3D Devices	Session co-chair: Neel Leslie	10:20 a.m. (Room 205)

User groups

Tuesday, October 6		
Focused Ion Beam User Group	Session moderator: Michael Wong	01:50 p.m. (Bridge Hall)
Wednesday, October 7		
Nanoprobng User Group	Session moderator: Tad Daniel, Presenter: Shelby Shackelford	10:40 a.m. (Bridge Hall)

Poster sessions

Thursday, October 8		
Planar Deprocessing of Upper Packaging Layers in a Logic Chip using a Plasma Focused Ion Beam (PFIB) Oxygen Source and XeF2 Gas Assist	Samartha Channagiri	03:00 p.m. (Exhibit Hall)
Automated Workflow for High-Precision Delaying and Failure Analysis in 7 nm Programmable Logic	Lay Lay Goh, Altera, with Thermo Fisher Scientific	03:00 p.m. (Exhibit Hall)

Tutorial program

Sunday, October 4		
Fundamental Considerations in the Justification, Design, & Construction of an Analytical Laboratory for High-Tech Imaging & Processing Tools	Presenter: Steven Herschbein, with Thermo Fisher Scientific	08:00 a.m. (Room 205)
Correlative In-Situ AFM-in-SEM Technique for Advanced Semiconductor Failure Analysis and Material Characterization	Presenter: Jan Neuman, Nenovision, with Thermo Fisher Scientific	09:00 a.m. (Room 206 B)
An Introduction to the FIB (Focused Ion Beam) as a Microchip Circuit Edit Tool	Presenter: Steven Herschbein, with Thermo Fisher Scientific	10:20 a.m. (Room 205)

Sponsored events

Monday, October 5		
Tools of the Trade: Ga-Free Sample Preparation and Electron Beam-Based Fault Isolation for Advanced Device Analysis	Adam Stokes and Neel Leslie	05:30 p.m. (Exhibit Hall)
Wednesday, October 7		
Social Networking Dinner: Tickets required.		06:00 p.m. (Casa Rio Restaurant)

Visit us in the
exhibit hall at
booth #501

Stop by and meet with
our experts to discuss:

- TEM characterization
- Sample preparation
- Electrical fault isolation
- 3D visualization
- and much more

Our team has
specialized expertise
in each category.

Sign up for a meeting
to see a complete
list of topics.

Booth hours:

- Tuesday, October 6
9:30 a.m. to 6 p.m.
- Wednesday, October 7
9:30 a.m. to 4 p.m.



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